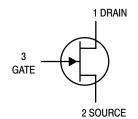


JFETs Switching

N-Channel - Depletion



MPF4392 MPF4393

ON Semiconductors Preferred Devices

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Drain-Source Voltage	V _{DS}	30	Vdc
Drain-Gate Voltage	V_{DG}	30	Vdc
Gate–Source Voltage	V _{GS}	30	Vdc
Forward Gate Current	I _{G(f)}	50	mAdc
Total Device Dissipation @ T _A = 25°C Derate above 25°C	PD	350 2.8	mW mW/°C
Operating and Storage Channel Temperature Range	T _{channel} , T _{stg}	-65 to +150	°C



ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic		Symbol	Min	Тур	Max	Unit	
OFF CHARACTERISTICS							
Gate–Source Breakdown Voltage ($I_G = 1.0 \mu Adc$, $V_{DS} = 0$)		V(BR)GSS	30	_	_	Vdc	
Gate Reverse Current (VGS = 15 Vdc, VDS = 0) (VGS = 15 Vdc, VDS = 0, TA = 100°C)		IGSS	<u>-</u>	_ _	1.0 0.2	nAdc μAdc	
Drain-Cutoff Current (V _{DS} = 15 Vdc, V _{GS} = 12 Vdc) (V _{DS} = 15 Vdc, V _{GS} = 12 Vdc, T _A = 100°C)		ID(off)	_ _	_ _	1.0 0.1	nAdc μAdc	
Gate Source Voltage (V _{DS} = 15 Vdc, I _D = 10 nAdc)	MPF4392 MPF4393	V _{GS}	-2.0 -0.5	_ _	-5.0 -3.0	Vdc	
ON CHARACTERISTICS							
Zero-Gate-Voltage Drain Current(1) (V _{DS} = 15 Vdc, V _{GS} = 0)	MPF4392 MPF4393	IDSS	25 5.0	_ _	75 30	mAdc	
Drain–Source On–Voltage $(I_D = 6.0 \text{ mAdc}, V_{GS} = 0)$ $(I_D = 3.0 \text{ mAdc}, V_{GS} = 0)$	MPF4392 MPF4393	VDS(on)	_ _	_ _	0.4 0.4	Vdc	
Static Drain–Source On Resistance (I _D = 1.0 mAdc, V _{GS} = 0)	MPF4392 MPF4393	rDS(on)	<u>-</u>	_ _	60 100	Ω	
SMALL-SIGNAL CHARACTERISTICS							
Forward Transfer Admittance (V _{DS} = 15 Vdc, I _D = 25 mAdc, f = 1.0 kHz) (V _{DS} = 15 Vdc, I _D = 5.0 mAdc, f = 1.0 kHz)	MPF4392 MPF4393	lyfsl	- -	17 12	_ _	mmhos	

^{1.} Pulse Test: Pulse Width $\leq 300 \,\mu\text{s}$, Duty Cycle $\leq 3.0\%$.

Preferred devices are ON Semiconductor recommended choices for future use and best overall value.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted) (Continued)

Characteristic			Min	Тур	Max	Unit
SMALL-SIGNAL CHARACTERISTICS (continued)	1				I.
Drain–Source "ON" Resistance (VGS = 0, ID = 0, f = 1.0 kHz)	MPF4392 MPF4393	^r ds(on)	- -	_ _	60 100	Ω
Input Capacitance ($V_{GS} = 15 \text{ Vdc}$, $V_{DS} = 0$, $f = 1.0 \text{ MHz}$)		C _{iss}	_	6.0	10	pF
Reverse Transfer Capacitance $(V_{GS} = 12 \text{ Vdc}, V_{DS} = 0, f = 1.0 \text{ MHz})$ $(V_{DS} = 15 \text{ Vdc}, I_D = 10 \text{ mAdc}, f = 1.0 \text{ MHz})$		C _{rss}	- -	2.5 3.2	3.5 -	pF
SWITCHING CHARACTERISTICS		1				
Rise Time (See Figure 2) (I _{D(on)} = 6.0 mAdc) (I _{D(on)} = 3.0 mAdc)	MPF4392 MPF4393	t _r	- -	2.0 2.5	5.0 5.0	ns
Fall Time (See Figure 4) (VGS(off) = 7.0 Vdc) (VGS(off) = 5.0 Vdc)	MPF4392 MPF4393	t _f	_ _	15 29	20 35	ns
Turn-On Time (See Figures 1 and 2) (ID(on) = 6.0 mAdc) (ID(on) = 3.0 mAdc)	MPF4392 MPF4393	t _{on}	_ _	4.0 6.5	15 15	ns
Turn-Off Time (See Figures 3 and 4) (VGS(off) = 7.0 Vdc) (VGS(off) = 5.0 Vdc)	MPF4392 MPF4393	^t off	_ _ _	20 37	35 55	ns

TYPICAL SWITCHING CHARACTERISTICS

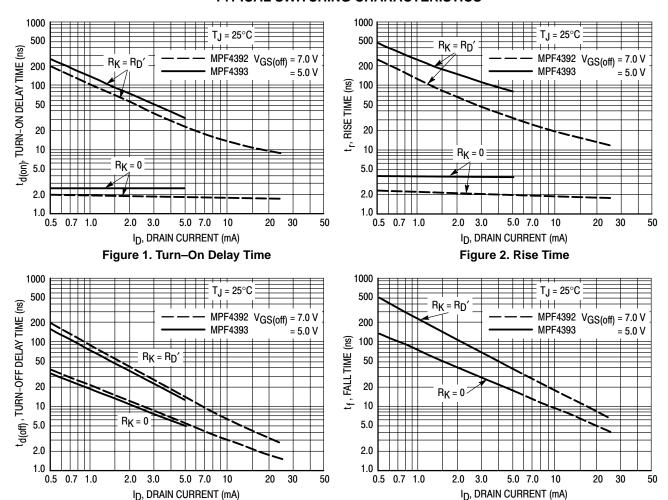


Figure 4. Fall Time

Figure 3. Turn-Off Delay Time

$-V_{DD}$ R_D SET VDS(off) = 10 V **INPUT** ₹R_{GEN} OUTPUT $\leq_{\mathsf{R}_{\mathsf{G}\mathsf{G}}}$ 50Ω 50 Ω VGG VGEN **INPUT PULSE** $R_{GG} \gg R_K$ $t_{\text{r}} \leq 0.25 \; \text{ns}$ $\mathsf{R}_\mathsf{D}' = \mathsf{R}_\mathsf{D}(\mathsf{R}_\mathsf{T} + 50)$ $t_f \le 0.5 \text{ ns}$ $R_D + R_T + 50$ PULSE WIDTH = 2.0 µs DUTY CYCLE ≤ 2.0%

Figure 5. Switching Time Test Circuit



The switching characteristics shown above were measured using a test circuit similar to Figure 5. At the beginning of the switching interval, the gate voltage is at Gate Supply Voltage (– V_{GG}). The Drain–Source Voltage (V_{DS}) is slightly lower than Drain Supply Voltage (V_{DD}) due to the voltage divider. Thus Reverse Transfer Capacitance (C_{rss}) or Gate–Drain Capacitance (C_{gd}) is charged to $V_{GG} + V_{DS}$.

During the turn—on interval, Gate—Source Capacitance (C_{gS}) discharges through the series combination of R_{Gen} and R_K . C_{gd} must discharge to $V_{DS(on)}$ through R_G and R_K in series with the parallel combination of effective load impedance (R'_D) and Drain—Source Resistance (r_{dS}). During the turn—off, this charge flow is reversed.

Predicting turn—on time is somewhat difficult as the channel resistance r_{ds} is a function of the gate—source voltage. While C_{gS} discharges, V_{GS} approaches zero and r_{ds} decreases. Since C_{gd} discharges through r_{ds} , turn—on time is non—linear. During turn—off, the situation is reversed with r_{ds} increasing as C_{gd} charges.

The above switching curves show two impedance conditions: 1) R_K is equal to R_D ' which simulates the switching behavior of cascaded stages where the driving source impedance is normally the load impedance of the previous stage, and 2) $R_K = 0$ (low impedance) the driving source impedance is that of the generator.

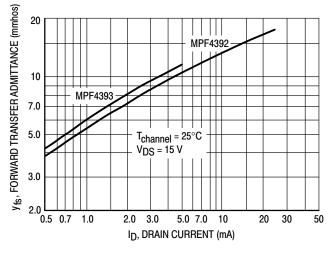


Figure 6. Typical Forward Transfer Admittance

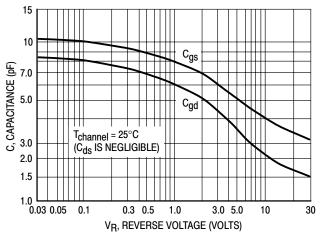


Figure 7. Typical Capacitance

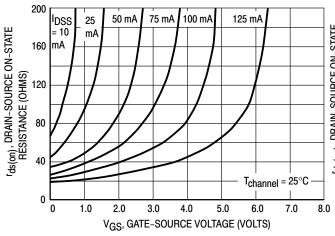


Figure 8. Effect of Gate-Source Voltage On Drain-Source Resistance

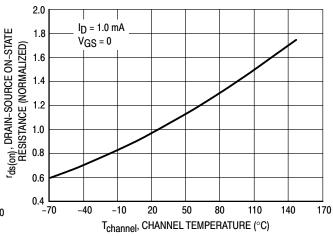


Figure 9. Effect of Temperature On Drain–Source On–State Resistance

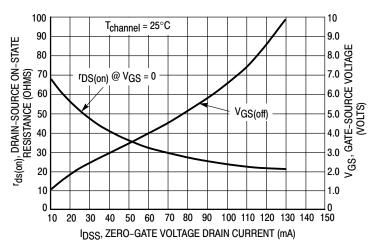


Figure 10. Effect of IDSS On Drain-Source Resistance and Gate-Source Voltage

NOTE 2

The Zero–Gate–Voltage Drain Current (IDSS), is the principle determinant of other J–FET characteristics. Figure 10 shows the relationship of Gate–Source Off Voltage (VGS(off)) and Drain–Source On Resistance (rds(on)) toIDSS. Most of the devices will be within $\pm 10\%$ of the values shown in Figure 10. This data will be useful in predicting the characteristic variations for a given part number.

For example:

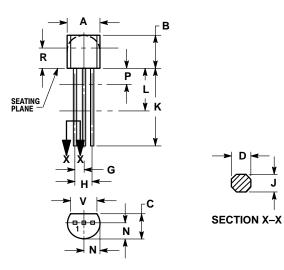
Unknown

r_{ds(on)} and V_{GS} range for an MPF4392

The electrical characteristics table indicates that an MPF4392 has an IDSS range of 25 to 75 mA. Figure 10 shows $r_{ds(on)}$ = 52 Ohms for IDSS = 25 mA and 30 Ohms for IDSS = 75 mA. The corresponding VGS values are 2.2 volts and 4.8 volts.

PACKAGE DIMENSIONS

TO-92 (TO-226) CASE 29-11 ISSUE AL



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
 4. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

	INCHES		MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.175	0.205	4.45	5.20	
В	0.170	0.210	4.32	5.33	
С	0.125	0.165	3.18	4.19	
D	0.016	0.021	0.407	0.533	
G	0.045	0.055	1.15	1.39	
Н	0.095	0.105	2.42	2.66	
J	0.015	0.020	0.39	0.50	
K	0.500		12.70		
L	0.250		6.35		
N	0.080	0.105	2.04	2.66	
P		0.100		2.54	
R	0.115		2.93		
٧	0.135		3.43		



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